Homework #11: Due: 12/8/2011

1. De problem 8.8 from Jaeger

2. Give 5 examples of pin mount packaged devices and 5 examples of surface mount packaged devices, i.e., logic gates are typically pin-mount packaged.

3. Research the current state-of-the-art for wire-bonding and flip chip bonding. Write a paragraph about each method and be sure to include important materials (wire materials, bond pad materials, encapsulant materials) , geometries (wire diameter, pitch, bond pad size, number of pads), and processes. Search patents and refereed articles only, and please include references.

4. Flexible substrates/packaging has gotten a lot of attention recently. Give of an example of a current and a future application for a flexible package. Include a process flow and schematic of each device.